



Sheet 1 of 1

Form PTO-1449

Attorney Docket No.
S243 1020.4Serial No.
10/607,615

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Applicant
Goodson, et al.Filing Date
06/27/03Group
2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
PM	A	5,880,071	03/99	Parce et al.	204	453	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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Serial No.

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Applicant

Goodson, et al.

Filing Date

06/27/93

Group

2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TM	AA	5,869,894	02/97	Degani, et al.	257	723	
	AB	5,901,040	05/99	Cromwell, et al.	361	704	
	AC	6,025,208	02/00	Chui, et al.	438	50	
	AD	6,052,287	04/00	Palmer, et al.	361	767	
	AE	6,133,631	10/00	Belady	257	714	
	AF	6,137,693	10/00	Schwiebert, et al.	361	803	
	AG	6,191,945	02/01	Belady, et al.	361	704	
	AH	6,285,550	09/01	Belady	361	704	
TM	AI	6,297,551	10/01	Dudderar, et al.	257	723	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
TM	AJ	97212126.9	07/98	China	B01D	61/42	X	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

TM	AK	"Micro Channel Heat Exchanger for Cooling Electrical Equipment," Kawano, et al., American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1998; v. 361 - 3, p. 173 - 180						
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Form PTO-449

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Attorney Docket No.
S243 1020.4Serial No.
10/607,615Applicant
Goodson, et al.Filing Date
06/27/93Group
2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>JM</i>	BA	4,009,423	02/77	Wilson	361	385	
	BB	4,067,237	01/78	Arcella	73	204	
	BC	4,120,019	10/78	Arii, et al.	361	385	
	BD	4,151,548	04/79	Klein, et al.	357	82	
	BE	4,392,362	07/83	Little	62	514	
	BF	4,638,854	07/83	Noren	165	76	
	BG	4,675,783	06/87	Murase, et al.	361	385	
	BH	4,697,427	10/87	Niggemann, et al.	62	119	
<i>JM</i>	BI	4,829,432	05/89	Hershberger, et al.	361	424	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>JM</i>	BJ	"Experimental Study on an Enhanced Microchannel Heat Sink for Microelectronics Applications," Keska, et al., American Society of Mechanical Engineers, EEP; 1999, v. 26 (2), p. 1235 - 1259
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	Applicant Goodson, et al.	
	Filing Date 06/27/93	Group 2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>TM</i>	CA	4,858,093	08/89	Sturgeon	363	20	
	CB	4,938,280	07/90	Clark	165	80.4	
	CC	4,951,740	08/90	Peterson, et al.	165	32	
	CD	4,975,825	12/90	Huss, et al.	363	141	
	CE	5,010,292	4/91	Lyle, Jr.	323	274	
	CF	5,131,859	07/92	Bowen, et al.	439	194	
	CG	5,144,531	09/92	Go, et al.	361	382	
<i>TM</i>	CH	5,162,974	11/92	Currie	361	385	
	CI	5,199,165	4/93	Crawford, et al.	29	846	

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>TM</i>	CJ	"High Performance Forced Air Cooling Scheme Employing Microchannel Heat Exchangers," Kleiner, et al.,
		IEEE Transactions on Components, Packaging, and Manufacturing Tech., Part A, Dec 1995; v. 18, no. 4, p. 795- 804
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U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JM	DA	5,229,915	07/93	Ishibashi, et al.	361	385	
	DB	5,311,397	05/94	Harshberger, et al.	361	683	
	DC	5,313,099	05/94	Tata, et al.	287	717	
	DD	5,339,214	08/94	Nelson	361	695	
	DE	5,365,749	11/94	Porter	62	259.2	
	DF	5,461,541	10/95	Wentland, Jr. et al.	361	707	
	DG	5,471,850	12/95	Cowans	62	223	
JM	DH	5,504,650	04/96	Katsui, et al.	361	697	
	DI	5,504,924	04/96	Ohashi, et al.	375	800	

FOREIGN PATENT DOCUMENTS

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						Yes	No

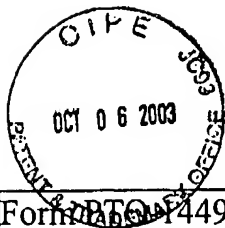
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JM	DJ	"Optimal Thermal Design of Air Cooled Forced Convection Finned Heat Sinks, Experimental Verification," Knight, et al., Conference: Intersociety Conference on Thermal Phenomena in Electronic Systems - I-Therm '92, 2/5 - 8/92, Austin, TX

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Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	EA	5,508,908	04/96	Kazama, et al.	363	141	
	EB	5,513,070	04/96	Xie, et al.	361	700	
	EC	5,544,412	08/96	Romero, et al.	29	832	
	ED	5,565,705	10/96	Romero, et al.	257	718	
	EE	5,579,827	12/96	Chung	165	80.3	
	EF	5,598,320	1/97	Toedtman, et al.	361	687	
	EG	5,608,262	3/97	Degani, et al.	257	723	
	EH	5,621,635	4/97	Takiar	363	141	
	EI	5,646,828	7/97	Degani, et al.	361	715	

FOREIGN PATENT DOCUMENTS

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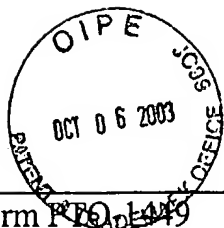
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	EJ	"Heat Transfer of Microstructures for Integrated Circuits," Koh, et al. International Communications in Heat and Mass Transfer; Jan - Feb 1986; v. 13, no. 1, p. 89 - 98.

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U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JM	FA	6,034,425	03/00	Chiang, et al.	257	697	
	FB	6,121,682	09/00	Kim	257	723	
	FC	6,127,726	10/00	Bright, et al.	257	691	
	FD	6,154,370	11/00	Degani, et al.	361	761	
	FE	6,201,302	03/01	Tzu	257	724	
	FF	6,204,562	03/01	Ho, et al.	257	777	
	FG	6,215,193	04/01	Tao, et al.	257	777	
	FH	6,268,660	07/01	Dhong, et al	257	774	
JM	FI	6,278,190	08/01	Tomita	257	777	

FOREIGN PATENT DOCUMENTS

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						Yes	No

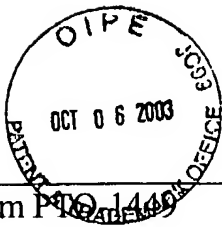
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JM	FJ	"Convection Cooling of Microelectronic Chips," Konecni, et al., Conference: Intersociety Conference on Thermal Phenomena in Electronic Systems - I-Therm '92, 2/5 - 8/92, Austin, Texas

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Form PTO-1462 INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>	Attorney Docket No. S243 1020.4	Serial No. 10/607,615
	Applicant Goodson, et al.	
	Filing Date 06/27/93	Group 2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JM	GA	6,335,566	01/02	Hirashima, et al.	257	686	
	GB	6,344,682	02/02	Tomita	257	686	
	GC	5,965,813	10/99	Wan, et al.	73	204.26	
	GD	5,965,001	10/99	Chow, et al.	204	600	
	GE	5,978,220	11/99	Frey, et al.	361	699	
	GF	5,997,713	12/99	Beetz, Jr., et al.	205	124	
	GG	5,998,240	12/99	Hamilton, et al.	438	122	
	GH	6,007,309	12/99	Hartley	417	322	
	GI	6,010,316	01/00	Haller, et al.	417	322	

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No

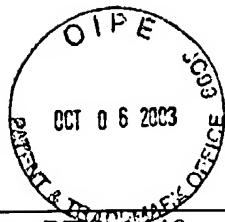
OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, etc.)*

JM	GJ	"Modeling of Two-Phase Microchannel Heat Sinks for VLSI Chips," Koo, et al., Proceedings of the IEEE Micro Electro Mechanical Systems (MEMS); 2001; p. 422 - 426

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Form PTO-1449

INFORMATION DISCLOSURE CITATION

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06/27/93Group
2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TM	HA	5,801,442	09/98	Hamilton, et al.	257	714	
	HB	5,835,345	11/98	Staskus, et al.	361	699	
	HC	5,836,750	11/98	Cabuz	417	322	
	HD	5,858,188	01/99	Soane, et al.	204	454	
	HE	5,863,708	01/99	Zanzucchi, et al.	430	320	
	HF	5,870,823	02/99	Bezama, et al.	29	848	
	HG	5,880,524	03/99	Xie	257	704	
	HH	5,901,037	05/99	Hamilton, et al.	361	699	
	HI	5,940,270	08/99	Pucket	361	699	

FOREIGN PATENT DOCUMENTS

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						Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

TM	HJ	"Simulation of Micro-Channel Heat Sinks for Optoelectronic Microsystems," Kreutz, et al., Microelectronics Journal;
		October 2000; v. 31, no. 9, p. 787 - 790

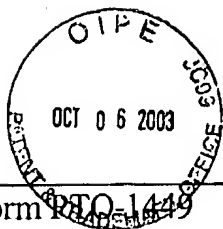
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U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TM	IA	6,013,164	01/00	Paul, et al.	204	450	
	IB	6,019,882	02/00	Paul, et al.	204	450	
	IC	6,054,034	04/00	Soane, et al.	204	601	
	ID	6,096,656	08/00	Matzke, et al.	438	702	
	IE	6,101,715	08/00	Fuesser, et al.	29	890.03	
	IF	6,129,145	10/00	Yamamoto, et al.	165	168	
	IG	6,146,103	11/00	Lee, et al.	417	50	
	IH	6,154,363	11/00	Chang	361	699	
TM	II	6,174,675	01/01	Chow, et al.	435	6	

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, etc.)*

TM	IJ	"Fabrication of Very Smooth Walls and Bottoms of Silicon Microchannels for Heat Dissipation of Semiconductor Devices," Dwivedi, et al., Microelectronics Journal; 2000; v. 31, no. 6, p. 405 - 410.

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U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JM	JA	6,210,986	01/01	Arnold, et al.	438	42	
	JB	6,216,343	04/01	Leland, et al.	29	890.032	
	JC	6,227,809	05/01	Forster, et al.	417	53	
	JD	6,234,240	05/01	Cheon	165	80.3	
	JE	6,238,538	05/01	Parce, et al.	204	600	
	JF	2001/0016985	08/21	Insley, et al.	29	890.039	
	JG	6,287,440	09/01	Arnold, et al.	204	450	
	JH	2001/0024820	09/01	Mastromatteo, et al.	435	287.2	
JM	JI	6,301,109	10/01	Chu, et al.	361	690	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JM	JJ	"Silicon Micromachining and Micromachines," Esashi, Wear; September 1, 1993; v. 168
		No. 1 - 2, p. 181 - 187

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Patent and Trademark Office; U. S. DEPARTMENT OF COMMERCE

Form PTO-144 INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	Attorney Docket No. S243 1020.4	Serial No. 10/607,615
	Applicant Goodson, et al.	
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U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>JM</i>	KA	6,313,992	11/01	Hildebrandt	361	700	
	KB	2001/0044155	11/01	Paul, et al.	436	161	
	KC	6,321,791	11/01	Chow	137	833	
	KD	6,322,753	11/01	Lindberg, et al.	422	192	
	KE	6,324,058	11/01	Hsiao	361	699	
	KF	2001/0046703	11/01	Burns, et al.	435	303.1	
	KG	3,923,426	12/75	Theeuwes	417	48	
	KH	4,312,012	01/82	Frieser, et al.	357	82	
<i>JM</i>	KI	4,450,472	05/84	Tuckerman, et al.	357	82	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>JM</i>	KJ	"Silicon Micromachining for Integrated Microsystems," Esashi, Vacuum; Jun - Aug 1996, v. 47, no. 6 - 8
		pp. 469 - 474

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JM	LA	4,516,632	05/85	Swift, et al.	165	167	
	LB	4,516,632	12/85	Eastman, et al.	361	385	
	LC	4,567,505	01/86	Pease, et al.	357	81	
	LD	4,573,067	02/86	Tuckerman, et al.	357	82	
	LE	4,758,926	07/88	Herrell, et al.	361	385	
	LF	4,868,712	09/99	Woodman	361	388	
	LG	4,894,709	01/90	Phillips, et al.	357	82	
JM	LH	4,908,112	03/90	Pace	204	299	

FOREIGN PATENT DOCUMENTS

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							Yes	No

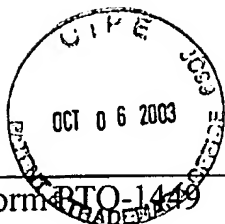
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JM	LJ	"Experimental evaluation of micro heat exchangers fabricated in silicon", Kuan, American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1996; v.331, p.131-136
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<i>JM</i>	MA	5,016,138	05/91	Woodman	361	381	
	MB	5,057,908	10/91	Weber	357	81	
	MC	5,070,040	12/91	Pankove	437	209	
	MD	5,083,194	01/92	Bartilson	357	81	
	ME	5,096,388	03/92	Weinberg	417	322	
	MF	5,099,311	03/92	Bonde, et al.	357	82	
	MG	5,125,451	06/92	Matthews	165	80.4	
<i>JM</i>	MH	5,099,910	03/92	Walpole, et al.	165	80.4	
<i>JM</i>	MI	5,131,233	07/92	Cray, et al.	62	64	

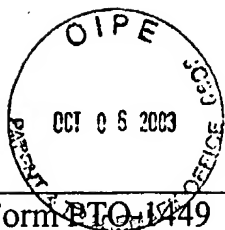
FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>JM</i>	MJ	"Flow characteristics of water through a microchannel between two parallel plates with electrokinetic effects", Mala et al., International Journal of Heat and Fluid Flow; Oct 1997; v.18, no.5, p.489-496
* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.		
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Form PTO-1449 INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	Attorney Docket No. S243 1020.4	Serial No. 10/607,615
	Applicant Goodson, et al.	
	Filing Date 06/27/93	Group 2811

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Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
JM	NA	5,203,401	04/93	Hamburgen, et al.	165	80.4	
	NB	5,218,515	06/93	Bernhardt	361	385	
	NC	5,219,278	06/93	Van Lintel	417	413	
	ND	5,230,564	07/93	Bartilson, et al.	374	178	
	NE	5,232,047	08/93	Matthews	165	168	
	NF	5,239,200	08/93	Messina, et al.	257	714	
	NG	5,263,251	11/93	Matthews	29	840.036	
	NH	5,274,920	01/94	Matthews	29	890.039	
	NI	5,281,026	01/94	Bartilson, et al.	374	143	

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	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JM	NJ	"Heat transfer and fluid flow in microchannels", Mala et al., International Journal of Heat and Mass Transfer; Sep 1997; v.40, no.13, p.3079-3088
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	Applicant Goodson, et al.	
	Filing Date 06/27/93	Group 2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>JM</i>	OA	5,309,319	05/94	Messina	361	699	
	OB	5,317,805	06/94	Hoopman, et al.	29	890.03	
	OC	5,325,265	06/94	Turlik, et al.	361	702	
	OD	5,336,062	08/94	Richter	417	413	
	OE	5,383,340	01/95	Larson, et al.	62	259.2	
	OF	5,427,174	06/95	Lomolino, Sr., et al.	165	1	
	OG	5,436,793	07/95	Sanwo, et al.	361	689	
	OH	5,459,099	10/95	Hsu	437	180	
<i>JM</i>	OI	5,508,234	04/96	Dusablon, Sr., et al.	437	228	

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
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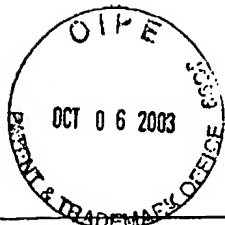
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>JM</i>	OJ	"Enhancement of Multichip Modules ("MCMs) cooling by incorporating microheatpipes and other high thermal conductivity materials into microchannel heat sinks", Marongiu et al., Proceedings -Electronic Components and Technology Conference; 1998; p.45-50
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Form PTO-1449

Attorney Docket No.
S243 1020.4Serial No.
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06/27/93Group
2811

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>JM</i>	PA	5,514,832	05/96	Dusablon, Sr., et al.	174	15.1	
	PB	5,514,906	05/96	Love, et al.	257	712	
	PC	5,575,929	11/96	Yu, et al.	216	10	
	PD	5,641,400	06/97	Kaltenbach, et al.	210	198.2	
	PE	5,692,558	12/97	Hamilton, et al.	165	80.4	
	PF	5,696,405	12/97	Weld	257	714	
	PG	5,703,536	01/98	Davis, et al.	330	289	
	PH	5,704,416	01/98	Larson, et al.	165	104.33	
<i>JM</i>	PI	5,727,618	03/98	Mundinger, et al.	165	80.4	

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						Yes	No

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, etc.)*

<i>JM</i>	PJ	"Integrated electroosmotic pumps and flow manifolds for total chemical analysis systems", Manz et al., Conference: 1991 International Conference on Solid-State Sensors and Actuators, 1991 Jun 24-28, San Francisco, CA, USA
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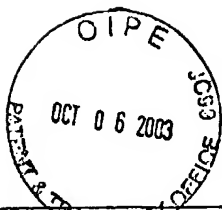
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TM	QA	5,759,014	06/98	Van Lintel	417	413.3	
	QB	5,763,951	06/98	Hamilton, et al.	257	714	
	QC	5,774,779	06/98	Tuchinskiy	419	2	
	QD	2001/0055714	12/01	Cettour-Rose, et al.	429	122	
	QE	6,337,794	01/02	Agonafer, et al.	361	690	
	QF	5,942,093	08/99	Rakestraw, et al.	204	450	
	QG	6,351,384	02/02	Daikoku, et al.	361	704	
TM	QH	6,186,660	02/01	Kopf-Still, et al.	366	340	

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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

TM	QI	"Electroosmotically induced hydraulic pumping with integrated electrodes on microfluidic devices", McKnight et al., Analytical Chemistry; Aug 15, 2001; v.73, no.16, p.4045-4049
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JM	RA	6,068,752	05/00	Dubrow, et al.	204	604	
	RB	6,090,251	07/00	Sundberg, et al.	204	453	
	RC	6,100,541	08/00	Nagle, et al.	250	573	
	RD	6171,067	01/01	Parce	417	48	
	RE	6,176,962	01/01	Soane, et al.	156	292	
	RF	6,210,986	04/01	Arnold, et al.	438	42	
	RG	6,221,226	04/01	Kopf-Sill	204	602	
	RH	6,277,257	08/01	Paul, et al.	204	450	
	RI	5,216,580	09/93	Davidson, et al.	361	385	
JM	RJ	5,560,423	10/96	Larson, et al.	165	104.26	

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JM	RK	"Microchannel heat sinks for two-dimensional high-power-density diode laser arrays", Missaggia et al., IEEE Journal of Quantum Electronics; Sep 1989; v.25, no.9, p.1988-1992
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OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, etc.)*

<i>TM</i>	SA	"Partial electroosmotic pumping in complex capillary systems. Part 1: Principles and general theoretical approach", Morf et al., Sensors and Actuators, B: Chemical; Feb 2001; v.72, no.3, p.266-272					
	SB	"High average power 2-D laser diode arrays on silicon microchannel collers", Mundinger et al., Conference: Conference on Lasers and Electro-Optics, 1989 Apr 24-28, Baltimore, MD, USA					
	SC	"Parametric optimization of multichanneled heat sinks for VLSI chip cooling", Murakami et al., IEEE Transactions on Components and Packaging Technologies; March 2001; v.24, no.1, p.2-9					
	SD	"Experimental investigation of heat transfer in flat plates with rectangular microchannets", Peng et al., International Journal of Heat and Mass Transfer; Jan 1995; v.38, no.1, p.127-137					
	SE	"Forced convection and flow boiling heat transfer for liquid flowing through microchannels", Peng et al., International Journal of Heat and Mass Transfer; Sep 1993; v.36, no.14, p.3421-3427					
	SF	"Enhancing the critical heat flux using microchanneled surfaces", Peng et al., Journal of Enhanced Heat Transfer; 1998; v.5, no.3, p.165-176					
	SG	"Cooling characteristics with microchannled structures", Peng et al., Journal of Enhanced Heat Transfer; 1994; v.1, no.4, p.315-326					
<i>TM</i>	SH	"Convective heat transfer and flow friction for water flow in microchannel structures", Peng et al., International Journal of Heat and Mass Transfer; Aug 1996; v.39, no.12, p.2599-2608					

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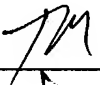


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							Yes	No

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	TA	"Heat transfer characteristics of water flowing through microchannels", Peng et al., Experimental Heat Transfer; Oct-Dec 1994; v.7, no. 4, p.265-283
	TB	"Microchannel integrated heat sinks in silicon technology", Perret et al., Conference Record - IAS Annual Meeting (IEEE Industry Applications Society); 1998; v.2, p.1051-1055
	TC	"Performance of a MEMS based micro capillary pumped loop for chip-level temperature control", Pettigrew et al., Proceedings of the IEEE Micro Electro Mechanical Systems (MEMS); 2001; p.427-430
	TD	"Liquid transport in micron and submicron channels", Pfahler et al., Sensors and Actuators, A: Physical; 3 Pt3 1990; v.22, no. 1-3, p.431-434
	TE	"Experimental measurements of fluid flow and heat transfer in microchannel cooling passages in a chip substrate", Rahman et al., American Society of Mechanical Engineers, EEP; 1993; v.4-2, p.685-692
	TF	"Flow rate measurement via conductivity monitoring in micro-fluidic devices", Rainey et al., Proceedings of SPIE - The International Society for Optical Engineering; 2000; v. 4177, p. 185-193
	TG	"Fabrication techniques to realize CMOS-compatible microfluidic microchannels", Rasmussen et al., Journal of Microelectromechanical Systems; June 2001; v. 10, no. 2, p.286-297
	TH	"Impact of channel geometry on two-phase flow heat transfer characteristics of refrigerants in microchannel heat exchangers", Ravigururajan, Journal of Heat Transfer, Transactions ASME; May 1998; v.120, no.2, p.485-491

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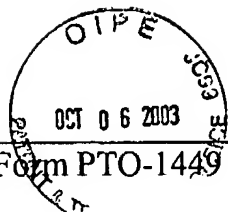
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>TM</i>	UA	"Liquid flow characteristics in a diamond-pattern micro-heat-exchanger", Ravigururajan et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division (Publication) DSC; 1996; v.59, p.159-166						
	UB	"Single-phase flow thermal performance characteristics of a parallel micro-channel heat exchanger", Ravigururajan et al., American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1996; v.329, no. 7, p.157-166						
	UC	"Effect of heat flux on two-phase flow characteristics of refrigerant flows in a micro-channel heat exchanger", Ravigururajan et al., American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1996; v.329, no. 7, p.167-178						
	UD	"Acousto-and electroosmotic microfluidic controllers", Rife et al., Proceedings of SPIE - The International Society for Optical Engineering; 1998; v.3515, p.125-135						
	UE	"Liquid flow and heat transfer in microchannels: A review", Rostami et al., Heat and Technology; 2000; v.18, no. 2, p.59-68"						
	UF	"Very high heat flux microchannel heat exchanger for cooling of semiconductor laser diode arrays", Roy et al., IEEE Transactions on Components, Packaging, and Manufacturing Technology Part B: Advanced Packaging; May 1996; v.19, no.2, p.444 - 451						
<i>TM</i>	UG	"Convective heat transfer in microchannels", Samalam, Journal of Electronic Materials, Vol. 18, pp. 611-617, 1989						

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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>PM</i>	VA	"Optimal structure for microgrooved cooling fin for high-power LSI devices", Sasaki, S.; Kishimoto, Electronics Letters; Dec 4, 1986; v.22, no. 25, p.1332-1334						
	VB	"Electroosmotic pumping and valveless control of fluid flow within a manifold of capillaries on a glass chip", Seiler, et al., Analytical Chemistry; October 15, 1994; v.66, no. 20, p.3485-3491						
	VC	"Micro heat spreader enhanced heat transfer in MCMs", Shen et al., Proceedings of the IEEE Multi-Chip Module Conference; January 31, 1995; p.189-194						
	VD	"Microflow devices and systems", Shoji et al., Journal of Micromechanics and Microengineering; Dec 1994; v.4, no.4, p.157-171						
	VE	"Overview of fabrication methods and fluid flow and heat transfer characteristics of micro channels", Sunden et al., Conference: Second Baltic Heat Transfer Conference, 1995 Aug 21-23, Jurmala, Latvia						
<i>OK</i>	VF	"Electrokinetic dewatering and thickening. I. Introduction and historical review of electrokinetic applications", Sunderland, J Appl Electrochem; Sep 1987; v.17, no.5, p.889-898						
<i>PM</i>	VG	"High-performance heat sinking for VLSI", Tuckerman et al., IEEE Electron Device Lett; May 1981; v.EDL-2, no. 5, p.126-129						

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<i>TM</i>	WA	"Analysis of two-layered micro-channel heat sink concept in electronic cooling", Vafal et al., International Journal of Heat and Mass Transfer; Jun 1999; v.42, no. 12, p.2287-2297						
	WB	"Two-phase flow in microchannels", Stanley, et al., Microelectromechanical Systems (MEMS), DSC-Vol. 62/HTD-Vol.254, p.143-152						
	WC	"Experimental investigation on liquid forced-convection heat transfer through microchannels", Wang et al., International Journal of Heat and Mass Transfer; Mar 1994; v.37, no. SUPPL 1, p.73-82						
	WD	"Analysis of microchannels for integrated cooling", Weisberg et al., International Journal of Heat and Mass Transfer; Oct 1992; v.35, no. 10, p. 2465-2474						
	WE	"Micro fluidic system of micro channels with on-site sensors by silicon bulk micromachining", Yang et al., Proceedings of SPIE - The International Society for Optical Engineering; 1999; v. 3877, p.267-272						
	WF	"Modeling forced liquid convection in rectangular microchannels with electrokinetic effects", Yang et al., International Journal of Heat and Mass Transfer; Dec 1998; v.41, no. 24, p.4229-4249						
<i>TM</i>	WG	"Uniform channel micro heat exchangers", Yin et al, Journal of Electronic Packaging, Transactions of the ASME; Jun 1997; v.119, no.2, p.89-93						
	WH	"Fabrication, Derivatization and Applications of Plastic Microfluidic Devices", Barker, et al., Proceedings of SPIE - The International Society for Optical Engineering, Nov. 2000, v.4205, p.112-118						

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Vafal M.K.

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OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, etc.)*

<i>TM</i>	XA	"Experimental and theoretical investigation of fluid flow and heat transfer in microtubes", Yu et al., ASME/JSME Thermal Engineering Joint Conference - Proceedings; 1995; v.1, p.523-530						
	XB	"Fabrication and characterization of electrokinetic micro pumps", Zeng et al., Thermomechanical Phenomena in Electronic Systems -Proceedings of the Intersociety Conference; 2000; v.2, p.31-36						
	XC	"Experimental study on local heat transfer with liquid impingement flow in two-dimensional microchannels", Zhuang et al., International Journal of Heat and Mass Transfer, Oct 1997, v.40, no. 17, p.4055-4059						
	XD	"Heat out of small packages", Joshi, Mechanical Engineering, Dec. 2001, p.56-58						
	XE	"Heat Exchange Element for Semiconductor Device Cooling", Edmonds, et al., IBM Technical Disclosure Bulletin, Aug 1980, v.23, no.3, p.1057						
	XF	"Liquid Cooling of Integrated Circuit Chips", Anacker, IBM Technical Disclosure Bulletin, Feb 1978, v.20, no.9, p.3742-3743						
<i>V</i>	XG	"Heat transfer from silicon chips and wafers", Noth, IBM Technical Disclosure Bulletin, May 1975, v.17, no.12, p.3544						
<i>TM</i>	XH	"Forced boiling cooling system with jet enhancement for critical heat flux extension", IBM Technical Disclosure Bulletin, Oct 1996, v.39, no. 10, p.143						

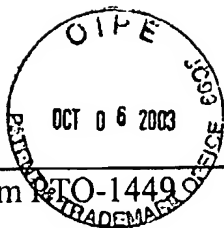
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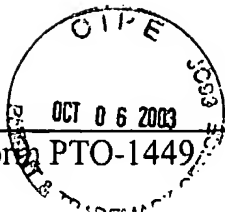
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<i>TM</i>	YA	"Miniature heat exchanger for corrosive media", IBM Technical Disclosure Bulletin, Jan 1995, v.38, no.01, p.55-56						
	YB	"Self-contained active heat dissipation device", IBM Technical Disclosure Bulletin, Apr 1996, v.39, no.04, p.115-116						
	YC	"Liquid jet cooling of integrated circuit chips", Sachar, IBM Technical Disclosure Bulletin, Feb 1978, v.20, no.9, p.3727-3728						
	YD	"Centerless ceramic package with directly connected heat sink", Ronkese, IBM Technical Disclosure Bulletin, Feb 1978, v.20, no.9, p.3577-3578						
	YE	"Jet cooling cup for cooling semiconductor devices", Keller, et al., IBM Technical Disclosure Bulletin, Feb 1978, v.20, no.9, p.3575-3576						
	YF	"Device cooling", Johnson, IBM Technical Disclosure Bulletin, Mar 1978, v.20, no.10, p.3919-3920						
	YG	"Integrated circuit module package cooling structure", Pascuzzo, et al., IBM Technical Disclosure Bulletin, Mar 1978, v.20, no.10, p.3898-3899						
<i>TM</i>	YH	"Integrated module heat exchanger", Antonetti, et al., IBM Technical Disclosure Bulletin, Apr 1978, v.20, no. 11A, p.4498						

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<i>TM</i>	ZA	"Temperature triggerable fluid coupling system for cooling semiconductor dies", Dorler, et al., IBM Technical Disclosure Bulletin, Apr 1978, v.20, no.11A, p.4386-4388						
	ZB	"Flexible thermal conductor for electronic module", Durand, et al., IBM Technical Disclosure Bulletin, Apr 1978, v.20, No.1 1A, p.4343						
	ZC	"Liquid cooling of a multichip module package", Balderes, et al., IBM Technical Disclosure Bulletin, Apr 1978, v.20, no.11A, p.4336-4337						
	ZD	"Conduction cooling module", Hwang, et al. IBM Technical Disclosure Bulletin, Apr 1978, v.20, no.1 1A, p.4334-4335						
	ZE	"Electronic packaging structure", Arnold, et al., IBM Technical Disclosure Bulletin, Apr 1978, v.20, no.11B, p.4820-4822						
	ZF	"High performance package for memory", Doo, et al., IBM Technical Disclosure Bulletin, July 1978, v.21, no.2, p.585-586						
<i>✓</i>	ZG	"Multi-chip package with cooling by a spreader plate in contact with a chip having cylindrical holes mating with an inverse frame providing water flow within its pins", IBM Technical Disclosure Bulletin, Oct 1988, v.31, no.5, p.141-142						
<i>TM</i>	ZH	"Cooling system for semiconductor chips", Landrock, et al., IBM Technical Disclosure Bulletin, Sep 1980, v.23, no.4, p.1483						

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<i>jm</i>	AAA	"Chip cooling", Krumm, IBM Technical Disclosure Bulletin, Dec 1977, v.20, no.7, p.2728						
	AAB	"Convection cooling apparatus", Damm, IBM Technical Disclosure Bulletin, Dec 1977, v.20, no.7, p.2755-2756						
	AAC	"TCM-like circuit module with local heat sink resting on chip and chip separated from coolant by bellows with pins and deflector plate attached to local heat sink and extending above bellows into region_of coolant flow", IBM Technical Disclosure Bulletin, Apr 1989, v.31, no.11, p.305-306						
	AAD	"Circuit module cooling with multiple pistons contacting a heat spreader/electrical buffer plate in contact with chip", IBM Technical Disclosure Bulletin, May 1989, v.31, no.12, p.5-7						
	AAE	"Circuit package with circulating boiling liquid and local heat exchanger to limit vapor in coolant outlet", IBM Technical Disclosure Bulletin, May 1989, v.31, no.12, p. ³⁴						
	AAF	"Water-cooled circuit module with grooves forming water passages near heat-producing devices", IBM Technical Disclosure Bulletin, May 1989, v.31, no.12, p.49-50						
	AAG	"Cold plate for thermal conduction module with only peripheral mounting bolts, large surface area fin inserts and reduced water flow and thermal resistances", IBM Technical Disclosure Bulletin, May 1989, v.31, no.12, p.59						
<i>jm</i>	AAH	"Thermal control hardware for accelerated run-in testing of multi-chip modules", IBM Technical Disclosure Bulletin, Oct 1989, v.32, no.5A, p.129-130						

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<i>TM</i>	ABA	"Means of removing more heat from a TCM (or other liquid-cooled logic package) by reducing the coolant temperature", IBM Technical Disclosure Bulletin, Oct 1989, v.32, no.5A, p.153-154
	ABB	"Liquid cooled module with compliant membrane", Loeffel, et al., IBM Technical Disclosure Bulletin, July 1977, v.20, no.2, p. 673-574
	ABC	"Method of effective cooling of a high power silicon chip", Doo, et al., IBM Technical Disclosure Bulletin, Sep 1977, v.20, no.4, p.1436-1437
	ABD	"Semiconductor chip cooling package", Doo, et al., IBM Technical Disclosure Bulletin, Sep 1977, v.20, no.4, p.1440-1441
	ABE	"Pin fin array heat pipe apparatus", IBM Technical Disclosure Bulletin, Sep 1994, v.37, no.09, p.171
	ABF	"Heat sink fabrication method", IBM Technical Disclosure Bulletin, Mar 1985, v.27, no.10A, p.5656-5657
<i>✓</i>	ABG	"Thermal conduction module with liquid dielectric and pistons with surface treatment for enhanced nucleate boiling", IBM Technical Disclosure Bulletin, May 1985, v.27, no.12, p.6904
<i>TM</i>	ABH	"Etched silicon integrated circuit heat sink", Brady, et al., IBM Technical Disclosure Bulletin, June 1984, v.27, no.1B, p.627

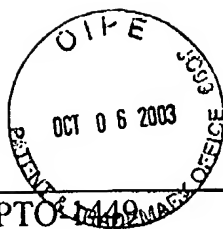
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	ACB	"Heat-pipe vapor cooling etched silicon structure", Eldridge, et al., IBM Technical Disclosure Bulletin, Jan 1983, v.25, no.8, p.4118-4119						
	ACC	"Silicon heat sink for semiconductor ship", Chu, et al., IBM Technical Disclosure Bulletin, Apr 1982, v.24, no.11A, p.5743						
	ACD	"Data processor cooling with connection to maintain flow through standby pump", Goodman, IBM Technical Disclosure Bulletin, Dec 1983, v.26, no.7A, p.3325						
	ACE	"Cooling system for data processor with flow restricter in secondary loop to limit bypass-cooling water flow", Gallagher, et al., IBM Technical Disclosure Bulletin, Oct 1983, v.26, no.5, p.2658						
	ACF	"Cold plate for thermal conduction module with improved flow pattern and flexible base", Hwang, et al., IBM Technical Disclosure Bulletin, Feb 1983, v.25, no.9, p.4517						
	ACG	"Structure for the removal of heat from an integrated circuit module", Arnold, IBM Technical Disclosure Bulletin, Nov 1979, v.22, no.6, p.2294-2296						
TM	ACH	"Heat sink design for cooling modules in a forced air environment", Arnold, et al., IBM Technical Disclosure Bulletin, Nov 1979 v.22, no.6, p.2297-2298						

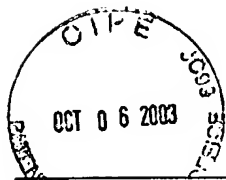
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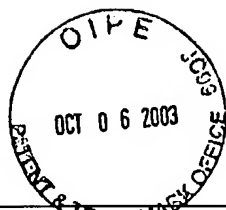
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<i>jm</i>	ADA	"Distributed power/thermal control", Chrisfield, et al, IBM Technical Disclosure Bulletin, Aug 1979, v.22, no. 3, p.1131-1132						
	ADB	"Liquid-filled bellows heat sink", Kleinfelder, et al., IBM Technical Disclosure Bulletin, Mar 1979, v.21, no. 10, p.4125-4126						
	ADC	"Cooling device for controlled rectifier", Bailey et al., IBM Technical Disclosure Bulletin, Apr 1979, v.21, no. 11, p.4609-4610						
	ADD	"Silicon heat sink method to control integrated circuit chip operating temperatures", Ahearn, et al., IBM Technical Disclosure Bulletin, Jan 1979, v.21, no. 8, p.3378-3380						
	ADE	"Chip cooling device", IBM Technical Disclosure Bulletin, Feb 1988, v.30, no. 9, p. 435-436						
	ADF	"Cooling system for chip carrier on card", IBM Technical Disclosure Bulletin, Sep 1988, v.31, no. 4, p.39-40						
<i>✓</i>	ADG	"Piping system with valves controlled by processor for heating circuit modules in a selected temperature profile for sealing integrity test under temperature stress", IBM Technical Disclosure Bulletin, Oct 1987, v.30, no. 5, p.336						
<i>jm</i>	ADH	"Circuit module cooling with coaxial bellows providing inlet, outlet and redundant connections to water-cooled element", IBM Technical Disclosure Bulletin, Oct 1987, v.30, no. 5, p.345-347						

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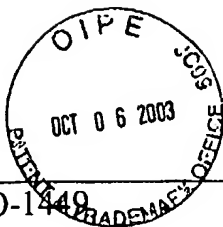
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<i>jm</i>	AEA	"Cold plate for thermal conduction module with inlet for cooling water near highest power chips", IBM Technical Disclosure Bulletin, Oct 1987, v.30, no. 5, p.413
	AEB	"Heat exchanger modules for data processor with valves operated by pressure from cooling water pump", IBM Technical Disclosure Bulletin, Oct 1987, v. 30, no. 5, p.419
	AEC	"Enhanced cooling of thermal conduction module", IBM Technical Disclosure Bulletin, Oct 1987, v.30, no. 5, p.426
	AED	"Integrally grooved semiconductor chip and heat sink", IBM Technical Disclosure Bulletin, Oct 1971, v.14, no. 5, p.1425
	AEE	"Structure for cooling by nucleate boiling", Riseman, IBM Technical Disclosure Bulletin, Apr 1976, v.18, no. 11, p.3700
	AEF	"Process for nucleate boiling enhancement", Chu, et al., IBM Technical Disclosure Bulletin, Dec 1975, v.18, no. 7, p.2227
<i>jm</i>	AEG	"Electroerosion micropump", IBM Technical Disclosure Bulletin, May 1990, v.32, no. 12, p.342-343
<i>jm</i>	AEH	"Thin heat pipe for cooling components on printed circuit boards", IBM Technical Disclosure Bulletin, Dec 1991, v.34, no. 7B, p.321-322

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<i>jm</i>	AFA	"A heat transfer enhancement method for forced convection bonded-fin heatsinks", Waldvogel, Motorola Technical Developments, Dec 1997, p.158-159						
	AFB	"Aluminum silicon carbide phase change heat spreader", Waidvogel, Motorola Technical Developments, June 1999, p.226-230						
	AFC	"An idea for maintaining a stable thermal environment for electronic devices", Slupe, et al., Research Disclosure, Aug 2001, p.13 12						
	AFD	"Autonomous displacement of a solution in a microchannel by another solution", Research Disclosure, June 2001, p.1046						
	AFE	"Thermal ink jet print head carriage with integral liquid cooling capabilities", Barner, et al., Xerox Disclosure Journal, Feb 1996, v.21, no.1, p.33-34						
	AFF	"Semiconductor laser body heat sink", Tramontana, Xerox Disclosure Journal, Dec 1985, v.10, no.6, p379-381						
<i>✓</i>	AFG	"Heat generation and transport in sub-micron semiconductor devices", Fushinobu et al., American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1993; v.253, p.21-28						
<i>jm</i>	AFH	"Integrated micro heat sink for power multichip module", Gillot et al., IEEE Transactions on Industry Applications; Jan-Feb 2000; v.36, no.1, p.217-221						

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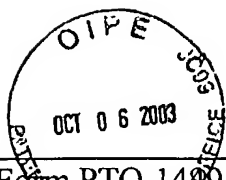
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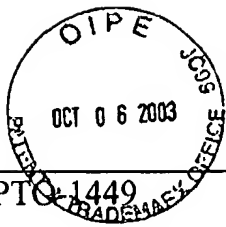
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<i>TM</i>	AGA	"Integrated single and two-phase micro heat sinks under IGBT chips", Gillot et al., IEEE Transactions on Components and Packaging Technologies; 1999; v.22, no.3, p.384-389						
	AGB	"Microchannel heat exchangers: a review", Goodling, Proceedings of SPIE - The International Society for Optical Engineering; 1993; v.1997, p.66-82						
	AGC	"Partial electroosmotic pumping in complex capillary systems. Part 2: Fabrication and application of a micro total analysis system suited for continuous volumetric nanotitrations", Guenat et al., Sensors and Actuators, B: Chemical; Feb 2001; v.72, no. 3, p.273-282						
	AGD	"Micro-channel heat exchanger optimization", Harpole et al., Proceedings - IEEE Semiconductor Thermal and Temperature Measurement Symposium; Feb 1991; p.59-63						
	AGE	"Design and fabrication of a cross flow micro heat exchanger", Harris et al., Journal of Microelectromechanical Systems; Dec 2000; v.9, no.4, p.502-508						
	AGF	"Electroosmotic pumping within a chemical sensor system integrated on silicon", Harrison et al., Conference: 1991 International Conference on Solid-State Sensors and Actuators, 1991 Jun 24-28, San Francisco, CA, USA						
<i>TM</i>	AGG	"Nonuniform temperature distribution in electronic devices cooled by flow in parallel microchannels", Hetsroni et al., IEEE Transactions on Components and Packaging Technologies; March 2001; v.24, no.1, p.16-23						
<i>TM</i>	AGH	"Fused quartz substrates for microchip electrophoresis", Jacobson et al., Analytical Chemistry; July 1, 1995; v.67, no.13, p.2059-2063						

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<i>JM</i>	AHA	"Thermal-hydraulic performance of small scale micro-channel and porous-media heat-exchangers", Jiang et al., International Journal of Heat and Mass Transfer; Mar 2001; v.44, no.5, p.1039-1051						
	AHB	"Fabrication and characterization of a microsystem for a micro-scale heat transfer study", Jiang et al., Journal of Micromechanics and Microengineering; Dec 1999; v.9, no.4, p.422-428						
	AHC	"Micro-channel heat sink with integrated temperature sensors for phase transition study", Jiang et al., Proceedings of the IEEE Micro Electro Mechanical Systems (MEMS); 1999; p.159-164						
	AHD	"Heat-transfer microstructures for integrated circuits", Tuckerman, Dissertation submitted to Dept. of Electrical Engineering, Stanford University, Feb. 1984						
	AHE	"Micro heat exchangers fabricated by diamond machining", Friedrich, et al., Precision Engineering, v.16, no.1, Jan 1994, p.56-59						
	AHF	"Electroosmotic flow control in micro channels produced by scanning excimer laser ablation", Wagner et al., Proceedings of SPIE - The International Society for Optical Engineering; 2000; v.4088, p.337-340						
<i>✓</i>	AHG	"Thermal management in semiconductor device packaging", Mahalingam, Proceedings of the IEEE, v.73, no.9, Sep 1985, p.1396-1404						
<i>JM</i>	AHH	"Applicability of Traditional turbulent single-phase forced convection correlations to non-circular microchannels", Adams et al., International Journal of Heat and Mass Transfer, 1999; v.42, no.23, p.4411-4415						

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	AIB	"Liquid transport in rectangular microchannels by electroosmotic pumping", Arulanandam et al., Colloids and Surfaces A: Physicochemical and Engineering Aspects; 2000; v.161, no.1, p.89-102					
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	AIE	"Modular microchannel cooled heatsinks for high average power laser diode arrays", Beach et al., IEEE Journal of Quantum Electronics; Apr 1992; v.28, no.4, p.966-976					
	AIF	"Two-phase electronic cooling using mini-channel and micro-channel heat sinks: Part 2- flow rate and pressure drop constraints", Bowers et al., Journal of Electronic Packaging, Transactions of the ASME; Dec 1994; v.116, no.4, p.298-305					
<i>v</i>	AIG	"High flux boiling in low flow rate, low pressure drop mini-channel and micro-channel heat sinks", Bowers et al., International Journal of Heat and Mass Transfer; Jan 1994; v.37, no.2, p.321-332					
<i>mm</i>	AIH	"Microflow devices for miniaturized chemical analysis systems", Buettgenbach et al., Proceedings of SPIE - The International Society for Optical Engineering; 1998; v.3539, p.51-61					

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	AJB	"Optimum design of microchannel heat sinks", Choquette et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division (Publication) DSC; 1996; v.59, p.115-126						
	AJC	"Manifold microchannel heat sinks: Theory and experiment", Copeland et al., American Society of Mechanical Engineers, EEP; 1995; v.10-2, p.829-835						
	AJD	"Fabrication and testing of microchannel heat exchangers", Cuta et al, Proceedings of SPIE - The International Society for Optical Engineering; 1995; v.2640, p.152-160						
	AJE	"Forced convection heat transfer in parallel channel array microchannel heat exchanger", Cuta et al., American Society of Mechanical Engineers, Heat Transfer Division, (Publication) HTD; 1996; v.338, p.17-23						
	AJF	"Electroosmosis: A reliable fluid propulsion system for flow injection analysis", Dasgupta et al., Analytical Chemistry; June 1, 1994; v.66, no.11, p.1792-1798						
<i>V</i>	AJG	"Micromachining of buried micro channels in silicon", de Boer et al., Journal of Microelectromechanical Systems; 2000; v.9, no.1, p.94-103						
<i>TM</i>	AJH	"Forced convection boiling in a microchannel heat sink", Jiang et al., Journal of Microelectromechanical Systems; March 2001; v.10, no.1, p.80-87						

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Attorney Docket No.
S243 1020.4Serial No.
10/607,615Applicant
Goodson, et al.Filing Date
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2811

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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>TM</i>	AKA	"Laminar flow through microchannels used for microscale cooling systems", Jiang et al., Proceedings of the Electronic Technology Conference, EPTC; 1997; p.119-122						
	AKB	"Fabrication of monolithic microchanriels for IC chip cooling", Joo et al., Proceedings of the IEEE Micro Electro Mechanical Systems; 1995; p.362-367						
	AKC	"Performance test and analysis of silicon-based microchannel heat sink", Kang et al, Proceedings of SPIE - The International Society for Optical Engineering; 1999; v.3795, p.259-270						
	AKD	"Micro heat exchangers consisting of pin arrays", Yin, et al., Journal of Electronic Packaging, Mar. 1996, v.118, p.51-57						
	AKE	"Measurements of Heat Transfer in Microchannel Heat Sinks", Rahman, International Communications in Heat and Mass Transfer, May 2000, v.27, no.4, p.495-506						
	AKF	"Enhancement of Critical Heat Flux From High Power Microelectronic Heat Sources in a Flow Channel", Mudawar, et at., Journal of Electronic Packaging, Sept. 1990, v.132, p.241-248						
<i>Y</i>	AKG	"Closed-Loop Electroosmotic Microchannel Cooling System for VLSI Circuits", Jiang, et at., printed in Journal of MEMS, Jan. 2002						
<i>TM</i>	AKH	"Liquid Flows in Microchannels", Sharp, et al., CRC Press, 2002, Chapter 6, p.6-1 to 6-38						

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<i>AM</i>	ALA	"Fabrication and characterization of electrokinetic micro pumps", Zeng, et al., 2000 Inter Society Conference on Thermal Phenomena, May 2000, p.31 -35						
<i>TM</i>	ALB	"Thermal-hydraulic characteristic of micro heat exchangers", Wang, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1991 ,v.32, p.331-339						
<i>TM</i>	ALC	"Electrokinetic Generation of High Pressures Using Porous Microstructures", Paul, et al., Micro-total analysis systems, 1998, Banff, Canada 1998, p.49-52						

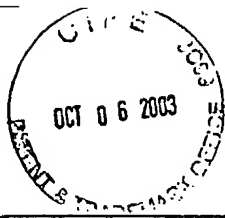
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<i>TM</i>	AMB	6,458,259	10/02	Parce et al.	204	454	

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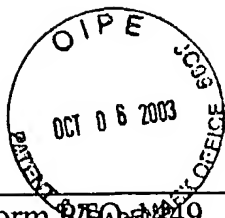
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<i>TM</i>	AMC	"Heat Transfer in Rectangular Microchannels;" Tunc, et al.; International Journal of Heat and Mass Transfer; February 2002; Vol. 45, no. 4, pp. 765 - 773
<i>TM</i>	AMD	"Measurements and Modeling of Two-Phase Flow in Microchannels with Nearly Constant Heat Flux Boundary Conditions;" Journal of Microelectromechanical Systems; February 2002; Vol. II, no. 1; pp. 12 - 19
<i>TM</i>	AME	"Micro-heat exchangers". Weisberg, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1990, v.19, p.159-17
<i>TM</i>	AMF	"Manufacturing and testing of compact micro heat exchangers with high volumetric heat transfer coefficients", Bier, et al.. American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1990, v19, p.189-197

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<i>pm</i>	ANA	"Design and fabrication of a cross flow micro heat exchanger". Harris et al., Journal of Microelectromechanical Systems; Dec 2000; v.9. no.4, p.502-508
<i>I</i>	ANB	"Two-phase electronic cooling using mini-channel and micro-channel heat sinks: Part I design criteria and heat diffusion constraints", Bowers. et al., Transactions of the ASME. Dec 1994, v.116. p.290-297
<i>d</i>	ANC	"Irrotationality of uniform electroosmosis", Cummings et al., Proceedings of SPIE -International Society for Optical Engineering; 1999; v.3877, p.180-189
<i>pm</i>	ANE	"Bibliography of liquid cooled heat sinks for thermal enhancement of electronic packages, Shaukatul I ah, IEEE Semiconductor Thermal Measurement and Management Symposium, 1999, p.231-245

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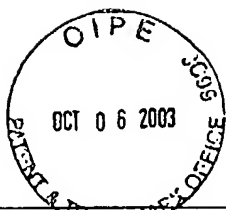
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<i>HM</i>	AOA	"Transient temperature performance of an integrated micro-thermal system", Jiang, et al., Journal of Micromechanics and Microengineering, Sep. 2000, v.10, p.466-476						
<i>I</i>	AOB	"Phase change in microchannel heat sinks with integrated temperature sensors", Jiang, et al., Journal of Microelectromechanical Systems, 1999, v.8. no. 4, p.358-365						
	AOC	"Electroosmotic pumping and electrophoretic separations for miniaturized chemical analysis systems", Manz, et al., J. Micromech. Microeng., 1994, p.257-265						
<i>↓</i>	AOD	"Micro-heat exchangers". Weisberg, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1990, v.19, p.159-17						
<i>TM</i>	AOE	"Manufacturing and testing of compact micro heat exchangers with high volumetric heat transfer coefficients", Bier, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1990, v.19, p.189-197						

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	APB	"Two-phase electronic cooling using mini-channel and micro-channel heat sinks: Part I design criteria and heat diffusion constraints", Bowers. et al., Transactions of the ASME. Dec 1994, v.116. p.290-297
	APC	"Active control of electroosmotic flow in microchannels using light", Moorthy et al., Sensors and Actuators, B: Chemical; May 15, 2001; v.75, no.3, p.223-229
<i>✓</i>	APD	"Irrotationality of uniform electroosmosis", Cummings et al., Proceedings of SPIE -International Society for Optical Engineering; 1999; v.3877, p.180-189
<i>jm</i>	APE	"Bibliography of liquid cooled heat sinks for thermal enhancement of electronic packages, Shaukatul I ah, IEEE Semiconductor Thermal Measurement and Management Symposium, 1999, p.231-245

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